



AUTOMOTIVE QUALIFIED 200V FRED ADDED TO A FAMILY OF POPULAR THINDPAK PACKAGED DEVICES

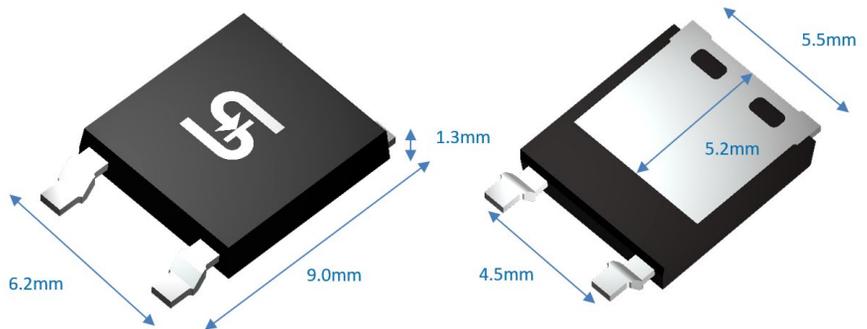
Taiwan Semiconductor(TSC), a global supplier of discrete power electronics devices, LED drivers, analog ICs and ESD protection devices, announces an additional 200V Ultra fast diode to the family of ThinDPAK devices.

KEY BENEFITS:

- Low profile (1.3mm height) ThinDPAK package.
- Ultra fast ($t_{rr} < 25\text{ns}$) reduces switching losses and improves efficiency.
- Footprint compatible with traditional DPAK package with 44% low profile to increase power density.
- Heatsink area is 20% larger than traditional DPAK package to reduce the thermal resistance.
- Operating temperature range from -55°C to 175°C .
- Automotive and Industrial grade available.

APPLICATIONS:

- High frequency switching
- DC/DC converters



Product Portfolio

Technology	Part Number	$V_{RRM}(V)$	$I_F(A)$	$V_F(V)$	$I_R(\mu A)$	$T_{rr}(ns)$	$T_J(^{\circ}C)$	Config.
UF Planar	PUAD4D(H)	200	4	0.92	2	25	175	Single
UF Planar	PUAD8D(H)	200	8	1.0	2	25	175	Single
UF Planar	PUAD6DC(H)	200	2*3	0.95	2	25	175	Common Cathode
UF Planar	PUAD8DC(H)	200	2*4	0.92	2	25	175	Common Cathode
UF Planar	PUAD10DC(H)	200	2*5	0.95	2	25	175	Common Cathode

* Adding "H" in the tail of Part Number are Automotive grade.

For more information or other products, please visit TSC website - <https://www.taiwansemi.com/>